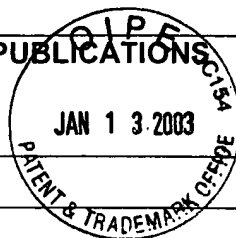


U.S. Department of Commerce, Patent and Trademark Office (PTO Form 1449 modified)		Docket No. APPM/5619	Serial No. 09/912,103
<b>SUPPLEMENTAL LIST OF PATENTS AND PUBLICATIONS CITED BY APPLICANT</b>		Applicant Nguyen, et al.	Confirmation No.: 4476
(Use several sheets if necessary)		Filing Date 07/23/2001	Group 2823
Examiner K. Nguyen			

**U.S. Patent Documents**

*Examiner Initial		Document Number	Issue Date	Applicant(s) Name	Class	Subclass	Filing Date If Appropriate
KN	A1	6,391,790	05/21/2002	Stoehr, et al.	438	715	07/25/2000
KN	A2	6,312,616	11/06/2001	Chinn, et al.	216	68	12/03/1998
KN	A3	6,277,763	08/21/2001	Kugimiyama, et al.	438	720	12/16/1999
KN	A4	6,251,217	06/26/2001	Ye, et al.	156	345	01/27/1999
KN	A5	6,221,784	04/24/2001	Schmidt, et al.	438	719	11/29/1999
KN	A6	6,214,637	04/10/2001	Kim, et al.	438	72	04/27/2000
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KN	A14	5,994,160	11/30/1999	Niedermann, et al.	438	53	09/27/1996
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Examiner

*K. Nguyen*

Date Considered

02/12/03

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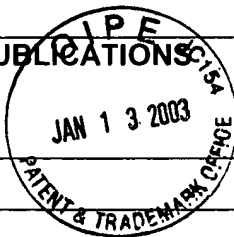
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		Nguyen, et al.	4476
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Examiner K. Nguyen		07/23/2001	2823

**Foreign Patent Documents**

*Examiner Initial		Document Number	Date	Country	Class	Subclass	Translation	
							YES	NO
KN	B1	27 01 458 A1	07/21/1977	DE	G03C	5/48	<input type="checkbox"/>	<input checked="" type="checkbox"/>
KN	B2	0 552 491 A1	07/28/1993	EP	H01J	37/32	<input type="checkbox"/>	<input type="checkbox"/>
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	B 24						<input checked="" type="checkbox"/>	<input type="checkbox"/>

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		Nguyen, et al.	4476
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**OTHER ART**

*Examiner Initial		Including Author, Title, Date, Pertinent Pages, Etc.
KN	C1	Search Report for PCT/US01/19282, dated May 31, 2002
KN	C2	Pan, et al., "Selective reactive ion etching of tungsten films in CHF <sub>3</sub> and other fluorinated gases", <i>J. Vac. Sci. and Tech. B</i> , 6(4), (July/August 1988), pp. 1073-1080
KN	C3	Theisen, et al., "Maskless Tungsten Etch Process for Plug Fill", <i>1046b Extended Abstracts</i> , Electrochem Soc., Spring Meeting, 90(1) (May 6-11, 1990), pp. 248-249
KN	C4	Ootera, et al., "Highly Selective Etching of W/WN/Poly-Si Gate on Thin Oxide Film With Gaspuff Plasmas", <i>Proc. of Symp. on Dry Process</i> (Nov. 11-12, 1999), pp. 155-160
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KN	C7	Khan, et al. "Plasma Etching of Silicon using Fluorinated Gas Mixtures," Filed March 5, 1999 USSN 09/263,634.
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	C13	
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